Type 11C Rackmountable Chassis System Overview

DESCRIPTION

Elma Type 11C family of enclosures provide a high quality, cost effective platform for packaging rackmount CompactPCI (2.0, 2.16, 2.17, 2.20, EXP.0) applications. Designed to IEEE 1101.10/.11 standards, Type 11C enclosures give advanced EMC shielding protection and are available with a wide range of options. Based on a modular packaging approach, the system can be configured by selecting the backplane, PSU, device modules and the number of slots. Engineered for superior cooling the Type 11C is available with either front to rear or bottom to top airflow. Standard heights are 3U-9U with custom sizes possible. The Type 11C will accept 3U or 6U cards mounted vertically or horizontally. Systems can be configured with or without rear I/O card cage.

TECHNICAL FEATURES:

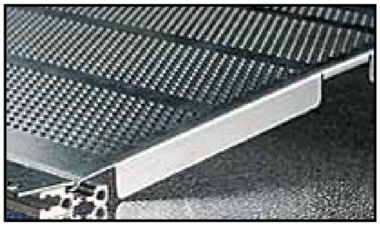
- Dimensions according to IEEE 1101.10/.11
- 160mm/80mm card guides with keying and ESD clip
- Advanced EMC shielding without gaskets, standard
- Rapid assembly
- Easy access for maintenance
- Sheet steel, pre-galvanized enclosure
- Aluminum extrusions, modules and panels
- Vibration resistant
- Designed to meet UL, CE, FCC and NEBS requirements

CONFIGURATION OPTIONS:

- Compatible with PICMG: 2.0, 2.16, 2.17, 2.20, EXP.0 (cPCI Express)
- H.110 Optional
- Mounting for 3U or 6U cPCI cards
- Vertical or horizontal card mounting
- Available heights 3U to 9U
- Rear I/O
- Standard 4, 6 and 8 slot backplanes
- Wide range of EMC shield peripheral modules
- Wide range of PSU options: fix mount, plug in, N+1
- 90-240VAC or 48VDC input
- Shelf Management: PICMG 2.9, IPMI

TYPE 11C

Front extrusions meet IEEE 1101.10 and CompactPCI Standard, specially designed for plug-in units with high insert/extract forces. The standard snap-fit and screw connections are suitable for demanding applications.



Typical attenuation for Type 11C